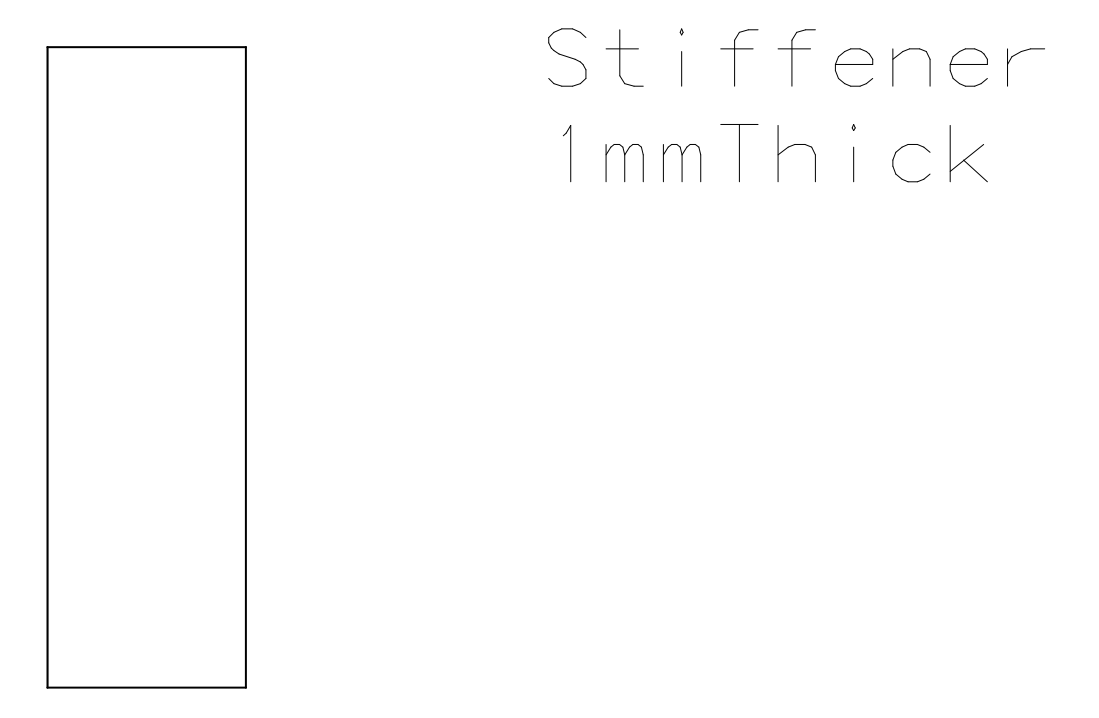
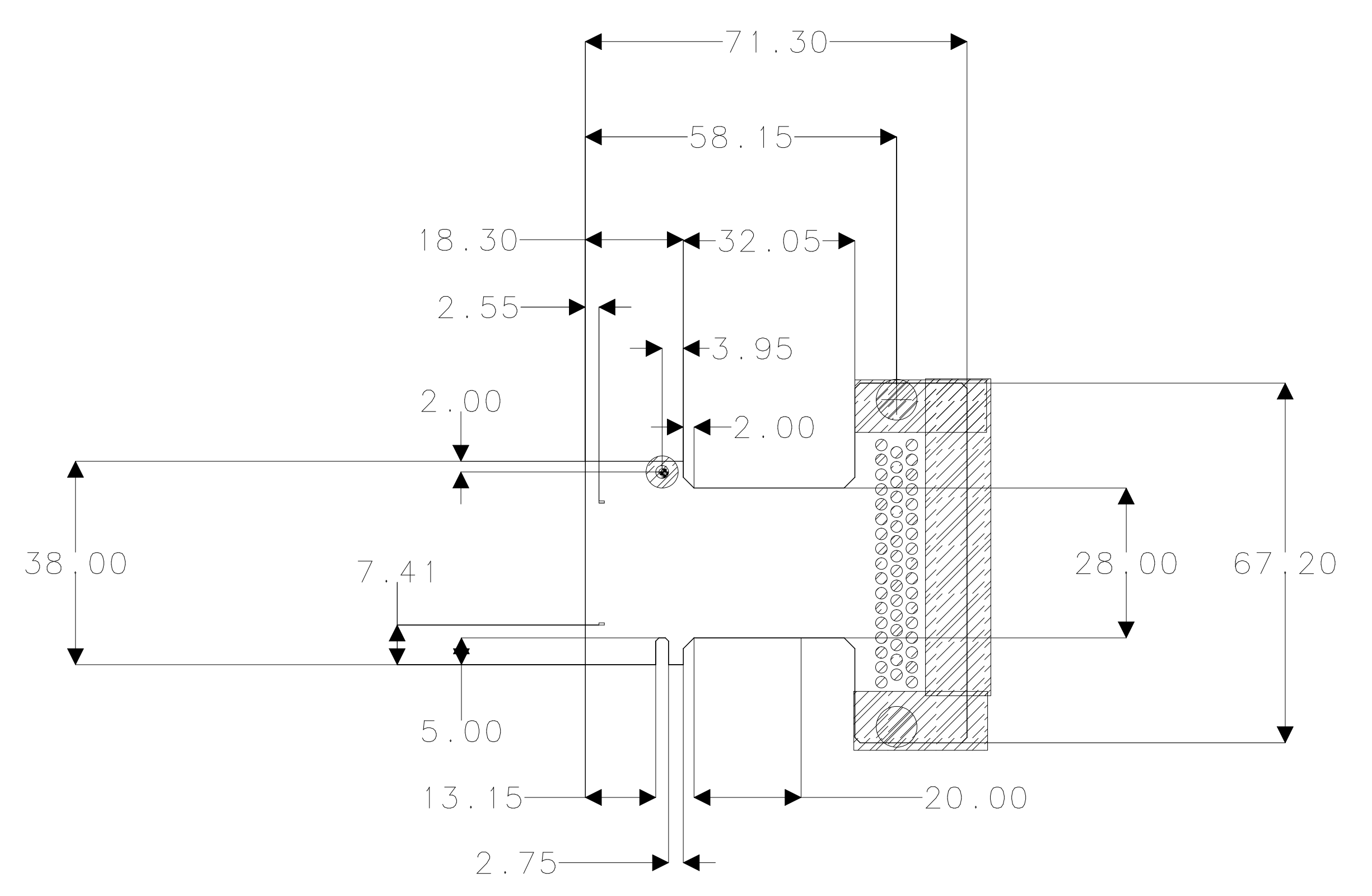


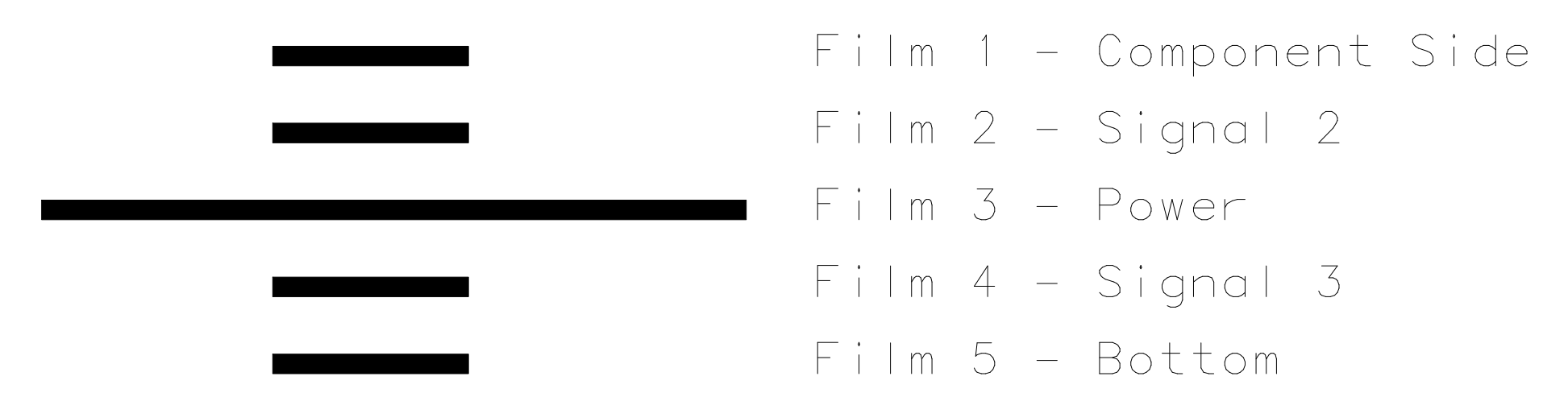
DWG. NO.	SH	REV.
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BOARD'S DRILL SCHEDULE

DRILL SYMBOL	DRILL SIZE	COUNT	PLATED	Tolerance	COMMENT
○	.00795	51	YES	---	
⊞	.05	50	YES	---	
⊕	.094488189	1	YES	---	
⊞	.12	2	YES	---	

Layer Order
5-Layer Flex PCB



- Board Characteristics
0. Material - RF775
 1. All dimensions in mm, unless specified
 2. Minimum trace width: 4 mils
 3. 0.5 Oz Copper on all layers
 4. Silkscreen on Component Side.
 5. Polyimide Coverlay (Kapton Soldermask) on Top and Bottom, as per Gerbers
 6. Soft Au finish (ENIG) for Al wire bonding and hand soldering on all pads.
 7. Place Stiffener on Top (Component) side of Flex PCB.
 8. Total flex circuit thickness cannot exceed 0.012", not including stiffener

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES .XX .XXX .XXX DO NOT SCALE DRAWING	CONTRACT NO.		UNIVERSITY OF CHICAGO ELECTRONICS DEVELOPMENT GROUP		
	APPROVALS	DATE	TITLE 1Kx6K/6Kx1K PA Flex Specification Drawing		
	DRAWN M. Bogdan	5/7/2021	SIZE B	FSCM NO.	DWG. NO. 2989
	CHECKED M. Bogdan	5/7/2021	ISSUED		REV. A
TREATMENT					
FINISH					
SIMILAR TO	ACT. WT	CALC WT	SCALE 1/1		SHEET